



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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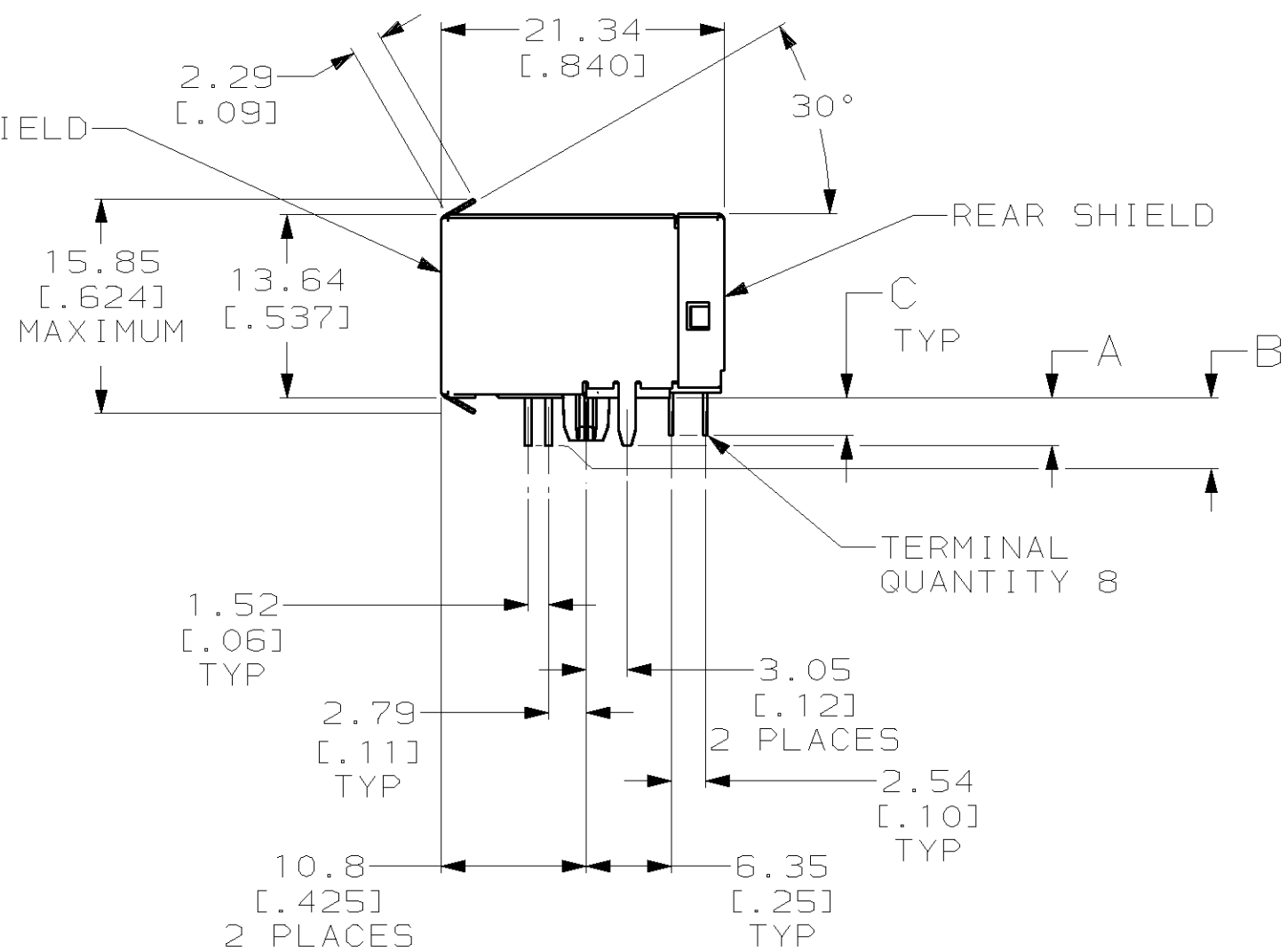
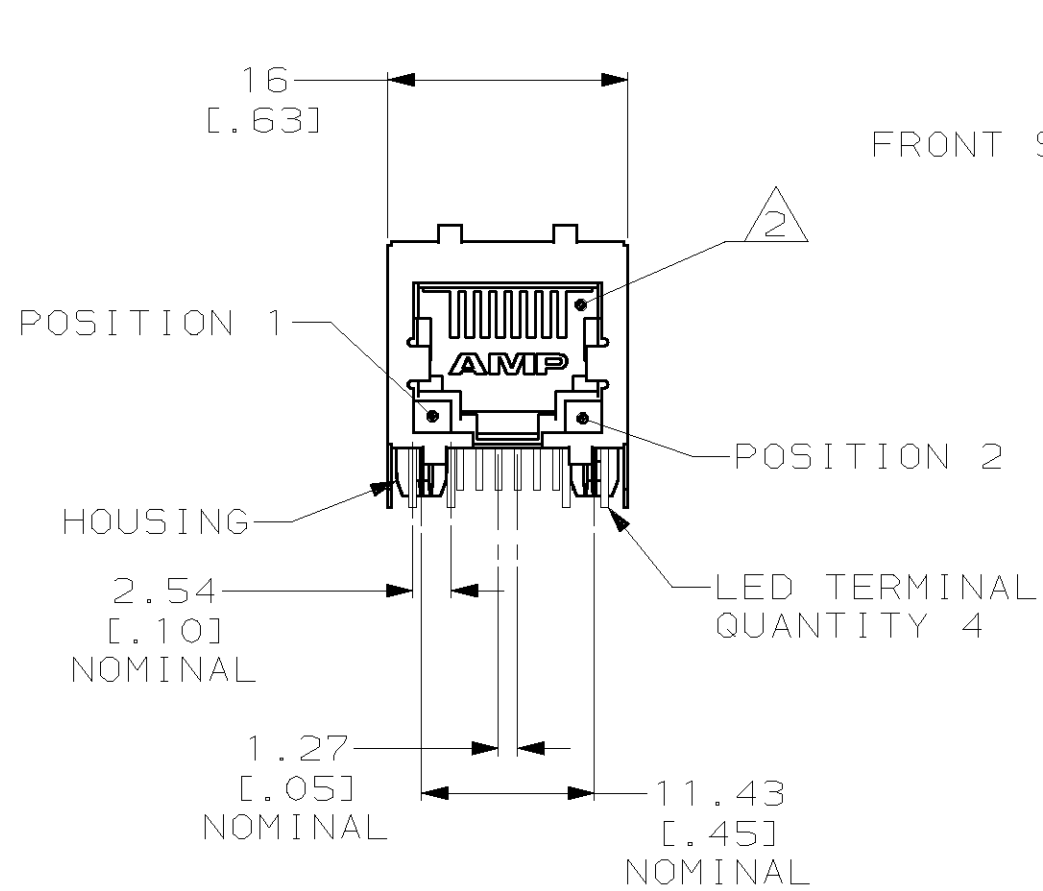
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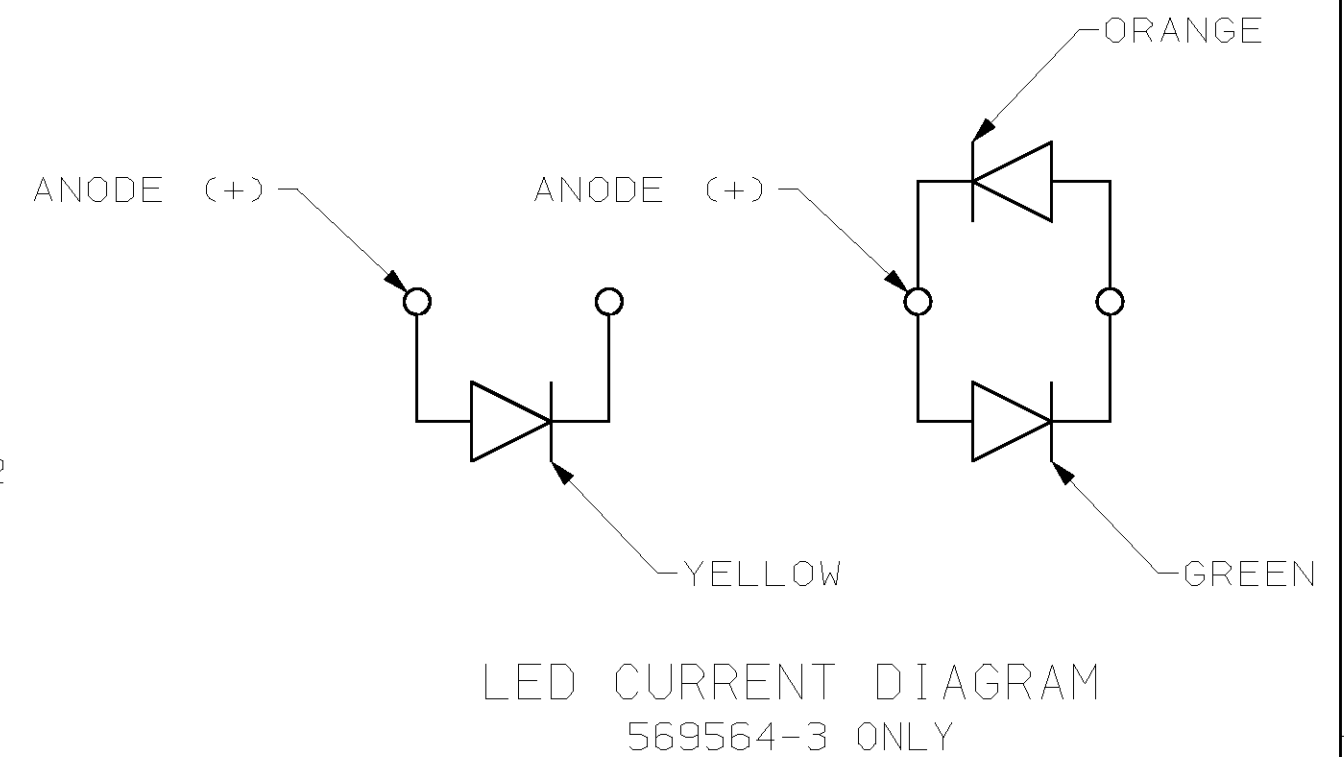
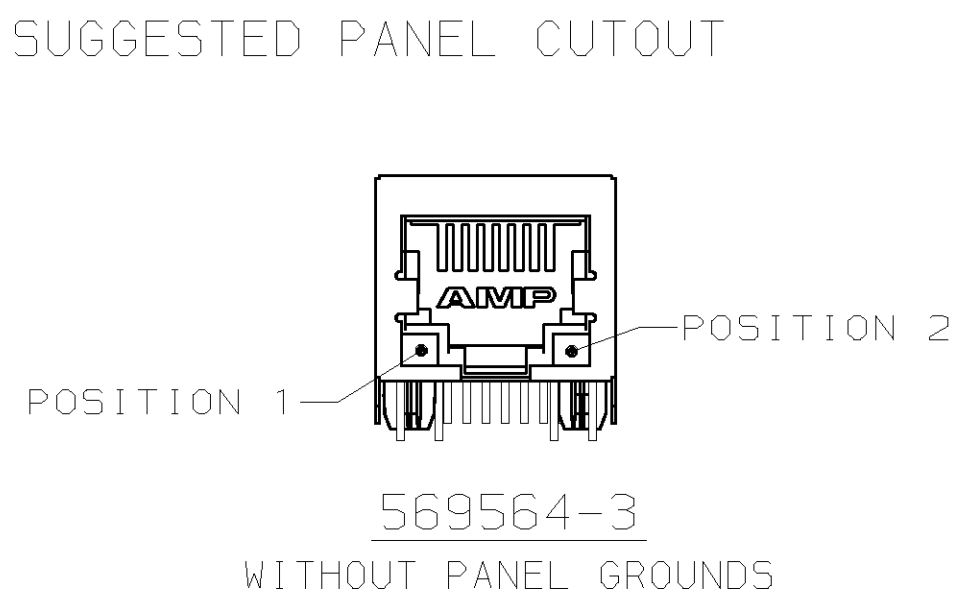
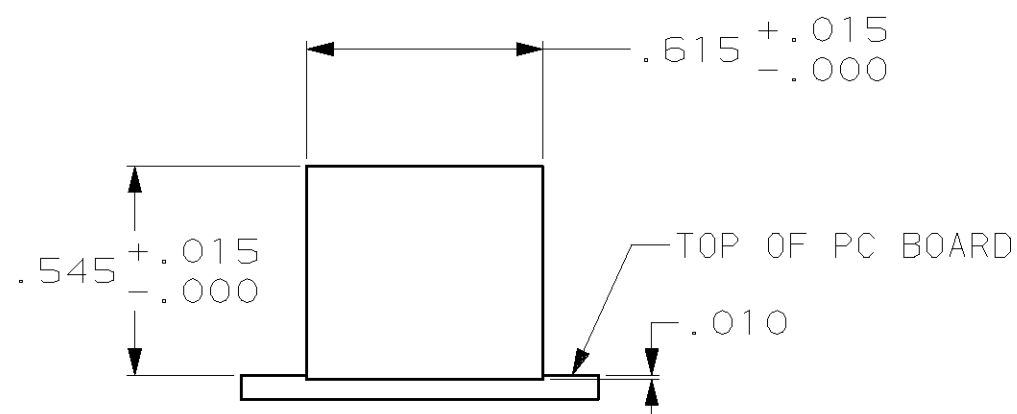
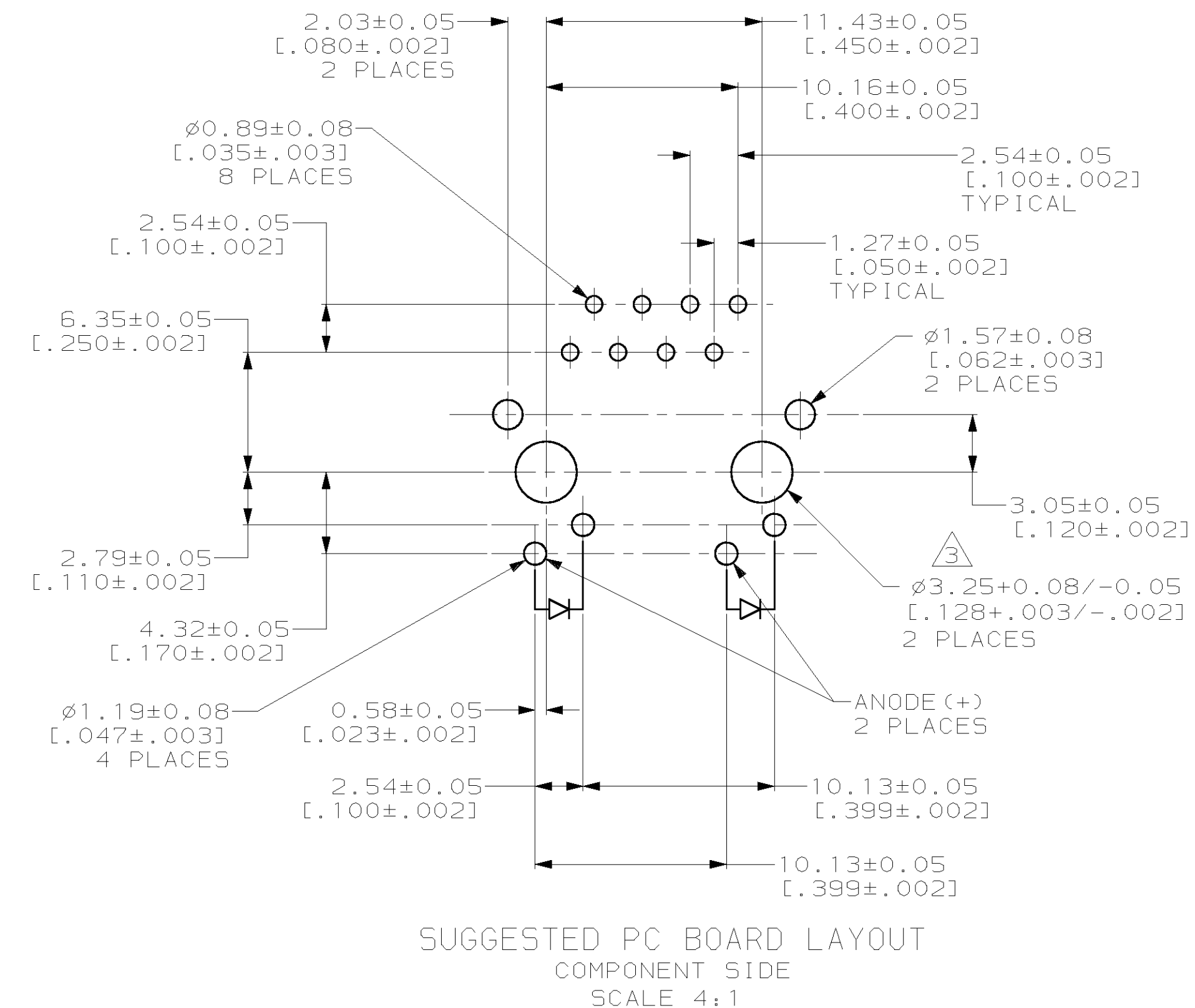


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LOC	DIST	REVISIONS					
		P	LTR	DESCRIPTION	DATE	DWN	APVD
AA	22		K	ADDED: -4 PER EC 0515-0283-02	08AUG02	DD	EL



- 1 MATERIAL: HOUSING - HIGH TEMPERATURE NYLON THERMOPLASTIC, BLACK, UL94V-0. TERMINALS - 0.33[.013] THICK PH05 BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MINIMUM THICK TIN-LEAD IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE. SHIELD - 0.254[.010] THICK COPPER ALLOY PLATED WITH 2.03µm[.000080] MINIMUM TIN-LEAD OVER 2.54µm[.000100] MINIMUM COPPER. LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 2.04µm[.000080] MINIMUM SILVER OVER 1.02µm[.000040] MINIMUM NICKEL UNDERPLATE OVER 1.02µm[.000040] MINIMUM COPPER UNDERPLATE.
- 2 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- 3 USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- 4. THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



C	B	A	LED COLOR		PART NUMBER
			POSITION 1	POSITION 2	
2.79 [.11]	3.56 [.14]	4.06 [.16]	GREEN	GREEN	569564-4
2.50 [.10]	2.50 [.10]	3.00 [.12]	YELLOW	GREEN/ORANGE	569564-3
2.79 [.11]	3.56 [.14]	4.06 [.16]	RED	YELLOW	569564-2
2.79 [.11]	3.56 [.14]	4.06 [.16]	GREEN	YELLOW	569564-1

SUPERSEDED BY 569564-1

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN T. SPRINKLE 06-SEP-95	AMP Incorporated Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK C. WHITT 27-SEP-95	AMP	
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ± 2 PLC ±0.25[.01] 3 PLC ±0.13[.005] 4 PLC ± ANGLES ±		APVD J. TONEY 04-OCT-95	NAME MODULAR JACK ASSEMBLY, 8 POSITION, RIGHT ANGLE, LOW PROFILE, PANEL GROUND WITH LEDS	
MATERIAL		PRODUCT SPEC 108-1163	SIZE A2	CAGE CODE 00779
FINISH		APPLICATION SPEC 114-2154	DRAWING NO C-569564	RESTRICTED TO
CUSTOMER DRAWING		WEIGHT -	SCALE 2:1	SHEET 1 OF 1
		REV K		